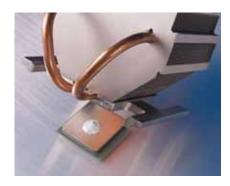
High Performance Thermal Interface Compound for Copper-Based Heat Sinks

Features and Benefits

- Thermal conductivity: 4.0 W/m-K
- Exceptional thermal performance: 0.19° C/W @ 50 psi



TIC 4000 is a thermally conductive grease compound designed for use as a thermal interface material between a computer processor and a copper-based heat sink. Other high watt density applications will benefit from the extremely low thermal impedance of TIC 4000.

TIC 4000 compound wets-out the thermal interface surfaces and flows to produce low thermal impedance. The compound requires pressure of the assembly to cause flow. TIC 4000 compound will not drip.

For a typical 0.5" x 0.5" application at 0.005" thick, Bergquist estimates approximately 0.02 ml (cc) of TIC 4000.

Although Bergquist estimates a 0.02 ml (cc) volumetric requirement for a 0.5" x 0.5" component interface, dispensed at a thickness of 0.005", Bergquist also recognizes that an optimized application would utilize the minimum volume of TIC 4000 material necessary to ensure complete wet-out of both mechanical interfaces.

PROPERTY	IMPERIAL VALUE		METRIC VALUE		TEST METHOD	
Color	Gray		Gray		Visual	
Density (g/cc)	4.0		4.0		ASTM D792	
Continuous Use Temp (°F) / (°C)	302		150			
ELECTRICAL						
Electrical Resistivity (Ohm-meter) (1)	N/A		N/A		ASTM D257	
THERMAL						
Thermal Conductivity (W/m-K)	4.0		4.0		ASTM D5470	
THERMAL PERFORMANCE vs PRESSU	IRE					
Press	sure (psi)	10	25	50	100	200
TO-220 Thermal Performance (°C/W) (2)		0.21	0.20	0.19	0.19	0.18

Application Methods

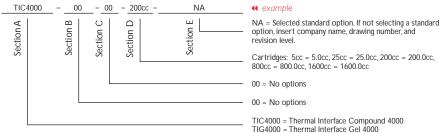
- Pre-clean heat sink and component interface with isopropyl alcohol prior to assembly or repair. Ensure heat sink is dry before applying TIC 4000.
- 2. Dispense TIC 4000 compound onto the processor or heat sink surface like thermal grease.
- 3. Assemble the processor and heat sink with clip or constant-pressure fasteners.

Typical Applications Include:

- High performance computer processors (traditional screw fastening or clamping methods will provide adequate force to optimize the thermal performance of TIC 4000)
- High watt density applications where the lowest thermal resistance interface is required

Building a Part Number

Standard Options



Note: To build a part number, visit our website at www.bergquistcompany.com.

TIC™: U.S. Patents 6,797,758; 6,624,224; 6,339,120.